











ARK Menu >

Intel® Core™ i3-4360 Processor (4M Cache, 3.70 GHz)

Recommended Customer Price

Specifications Essentials Performance **Memory Specifications Graphics Specifications Expansion Options Package Specifications Advanced Technologies** Intel® Data Protection Technology Intel® Platform **Protection Technology Compatible Products** Ordering / sSpecs / Steppings

Download Drivers

Specifications Essentials Launched Status Q2'14 Launch Date i3-4360 Processor Number Intel® Smart Cache 4 MB DMI2 5 GT/s Instruction Set 64-bit Instruction Set Extensions SSE4.1/4.2, AVX 2.0 Q Yes Embedded Options Available Lithography 22 nm Scalability 1S Only Thermal Solution Specification PCG 2013C

Conflict Free	Yes
Datasheet	Link
 Performance 	
Performance	
# of Cores	2
# of Threads	4
Processor Base Frequency	3.7 GHz
TDP	54 W

Memory Specifications	
Max Memory Size (dependent on memory type)	32 GB
Memory Types	DDR3-1333/1600, DDR3L- 1333/1600 @ 1.5V
Max # of Memory Channels	2
Max Memory Bandwidth	25.6 GB/s
ECC Memory Supported ‡	Yes

Graphics Specifications		
Processor Graphics ‡		Intel® HD Graphics 4600
Graphics Base Frequency		350 MHz
Graphics Max Dynamic Frequency		1.15 GHz
Graphics Video Max Memory		2 GB
Graphics Output		eDP/DP/HDMI/DVI/VGA
Max Resolution (HDMI 1.4)‡		4096x2304@24Hz
Max Resolution (DP)‡		3840x2160@60Hz
Max Resolution (eDP - Integrated Flat Panel)‡		3840x2160@60Hz
Max Resolution (VGA)‡		1920x1200@60Hz
DirectX* Support		11.2/12
OpenGL* Support		4.0
Intel® Quick Sync Video	Q	Yes
Intel® InTru™ 3D Technology		Yes
Intel® Wireless Display	Q	Yes
Intel® Clear Video HD Technology		Yes
# of Displays Supported ‡		3
Device ID		0x412

Expansion Options	
PCI Express Revision	Up to 3.0
PCI Express Configurations ‡	Up to 1x16, 2x8, 1x8+2x4
Max # of PCI Express Lanes	16

Package Specifications

Related Products

4th Generation Intel® Core™ i3 Processors

Compare

Intel® Core™ i3-4300 Desktop Processor Series Products formerly Haswell



Learn how Intel is pursuing conflict-free technology. >



Visit the Embedded Design Center >

Quick Links

Export Full Specifications > Find Compatible Boards > Search Distributors > Support Overview > Search all of intel.com >

PCN/MDDS Information

SR1PC 931890: PCN | MDDS 934992: PCN | MDDS

O I dekage opecifications	
Max CPU Configuration	1
T _{CASE}	72°C
Package Size	37.5mm x 37.5mm
Graphics and IMC Lithography	22 nm
Sockets Supported	FCLGA1150
Low Halogen Options Available	See MDDS
Advanced Technologies	
Intel® Turbo Boost Technology ‡	No
Intel® vPro Technology ‡	No
Intel® Hyper-Threading Technology ‡	Yes
Intel® Virtualization Technology (VT-x) ‡	Yes
Intel® Virtualization Technology for Directed I/O (VT-	
d) ‡	No
Intel® VT-x with Extended Page Tables (EPT) ‡	Yes
Intel® TSX-NI	No
Intel® 64 ‡	Yes
Idle States	Yes
Enhanced Intel SpeedStep® Technology	Yes
Thermal Monitoring Technologies	Yes
Intel® Stable Image Platform Program (SIPP)	No
Intel® Small Business Advantage	Yes
■ Intol® Data Protection Technology	
Intel® Data Protection Technology Intel® AES New Instructions	Yes
	=
Secure Key	Yes
Intel® Platform Protection Technology	
Trusted Execution Technology ‡	No
Execute Disable Bit ‡	Yes

All information provided is subject to change at any time, without notice. Intel may make changes to manufacturing life cycle, specifications, and product descriptions at any time, without notice. The information herein is provided "as-is" and Intel does not make any representations or warranties whatsoever regarding accuracy of the information, nor on the product features, availability, functionality, or compatibility of the products listed. Please contact system vendor for more information on specific products or systems.

"Intel classifications" consist of Export Control Classification Numbers (ECCN) and Harmonized Tariff Schedule (HTS) numbers. Any use made of Intel classifications are without recourse to Intel and shall not be construed as a representation or warranty regarding the proper ECCN or HTS. Your company may be the exporter of record, and as such, your company is responsible for determining the correct classification of any item at the time of export.

Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading-technology.html?wapkw=hyper+threading for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

The Recommended Customer Price ("RCP") is pricing guidance for Intel products. Prices are for direct Intel customers, typically represent 1,000-unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see http://www.intel.com/performance.

Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See http://www.intel.com/content/www/us/en/processors/processor-numbers.html for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

Send us your feedback!

Social About Support Legal Intel Communities Terms of Use Company Information Support Home Investor Relations Download Center *Trademarks Intel on Twitter Product Specifications (ARK) f Intel on Facebook Contact Us Privacy Cookies in Intel on LinkedIn Newsroom Supply Chain Transparency Site Map Intel on Instagram Intel on YouTube Jobs

